

IN THE CLAIMS:

Please cancel claims 1 through 8. Please add new claims 9 through 14.

9. (Added) A solder configuration, comprising a pad having a surface upon which an intermetallic boundary interface is disposed, said intermetallic boundary interface defining a separation between said pad and solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and circuitous, whereby a crack forming in said solder is influenced to proceed along said interface with a non-planar, circuitous path, thereby lengthening its travel, and preventing failure of said solder joint.

10. (Added) A solder configuration, comprising a pad having a surface upon which an intermetallic boundary interface is disposed, said intermetallic boundary interface defining a separation between said pad and solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and serpentine, whereby a

crack forming in said solder is influenced to proceed along said interface with a non-planar, serpentine path, thereby lengthening its travel, and preventing failure of said solder joint.

11. (Added) A solder configuration, comprising a pad having a surface upon which an intermetallic boundary interface is disposed, said intermetallic boundary interface defining a separation between said pad and solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and having a plurality of steps, whereby a crack forming in said solder is influenced to proceed along said interface with a non-planar, stepped path, thereby lengthening its travel, and preventing failure of said solder joint.

12. (Added) A solder configuration, comprising a pad having a surface upon which an intermetallic boundary interface is disposed, said intermetallic boundary interface defining a separation between said pad and solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and having a plurality of

concentric interruptions, whereby a crack forming in said solder is influenced to proceed along said interface with a non-planar, interrupted path, thereby lengthening its travel, and preventing failure of said solder joint.

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(cont)

13. (Added) A solder configuration, comprising a pad having a surface upon which an intermetallic boundary interface is disposed, said intermetallic boundary interface defining a separation between said pad and solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and having a plurality of interdigitated interruptions, whereby a crack forming in said solder is influenced to proceed along said interface with a non-planar, interrupted path, thereby lengthening its travel, and preventing failure of said solder joint.

14. (Added) A solder configuration, comprising a pad having a surface upon which an intermetallic boundary interface is disposed, said intermetallic boundary interface defining a separation between said pad and solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and having a cross-shaped